ASSOCIATION CONNECTING	■ Material Composit © Copyright 2005. IPC, international and Pan-Ar	Bannockb	ourn, Illinois. A	ll rights reserved nations.	under both	This docume level parts, t	ent is a declarat he declaration	ion of the su encompasse	ibstances v s all lower	within the manufactu level materials for v	urer listed which the u	item. Note: nanufacture	if the item is an as er has engineering	ssembly with low responsibility.	
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				e *	^c Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					als and Mfg Information				
upplier Informa	ation														
Company name* C			Company unique ID			Unique ID Authority				Respon	Response Date*				
onsemi											2024-04	2024-04-24			
Contact Name			Title - Contact				Phone - Contact*				Email -	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative				Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Requester	ester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	e Version Manufacturing Site			Weight*	UOM	Unit Type		
		NTMFS4C029NT3G		Trench 6 30V Nch			2024-04-24		M	MYE		107.2	mg	Each	
Ianufacturing P	Proccess Information	n													
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSL			L Rating	Peak Process Body Temperature Max Time at Peak				Temperature Number of Reflow Cycles				
Matte Tin (Sn) - annealed CU			CU Alloy	Alloy 1			260	0 C 30		30	seconds 3				
omments															
vel 1 - maximum tin	me at peak temperature o	during sol	dering is 10-3	0 seconds											
or more information	n regarding material con	position	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.73	mg	Supplier	Silicon (Si)	7440-21-3		0.73	mg
Die Attach Solder	2.41	mg	Supplier	Silver (Ag)	7440-22-4		0.0603	mg
			А	Lead (Pb)	7439-92-1	7a	2.2293	mg
			Supplier	Tin (Sn)	7440-31-5		0.1205	mg
Lead Frame	53.97	mg	Supplier	Zinc (Zn)	7440-66-6		0.0648	mg
			Supplier	Iron (Fe)	7439-89-6		1.2683	mg
			Supplier	Copper (Cu)	7440-50-8		52.6208	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0162	mg
Iold Compound-Black	43.54	mg		Epoxy resin	proprietary data		3.2655	mg
			Supplier	Phenolic Resin	Proprietary Data		1.0885	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.2655	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2177	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		35.7028	mg
Plating	1.7	mg	Supplier	Tin (Sn)	7440-31-5		1.7	mg
Wire Bond - Cu	0.05	mg	Supplier	Copper (Cu)	7440-50-8		0.05	mg